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900 Middlesex Turnpike, Building 6  
Billerica, MA 01821-3929

For further information:

Richard S. Post  
Chief Executive Officer  
978-932-2030

## NEXX Systems Launches New APOLLO Sputter Deposition System

**Billerica, MA – July 9, 2008** – NEXX Systems, a leading provider of processing equipment for advanced wafer-level packaging applications, today announced the product launch of its new **Apollo** sputter deposition system. The **Apollo** advances the state-of-the-art in metal deposition for wafer level packaging due to its remarkable versatility, excellent performance, and low cost of ownership. The **Apollo** is ideally suited for applications including under bump metallization, redistribution layers, backside metallization, integrated passives, LEDs. In addition, the **Apollo** is ideally suited for the metallization process required to produce solar panels, a growing application in today's initiatives for alternative energy production. Both the packaging and solar industries are driven to employ the most reliable and cost-effective solutions available for their metallization needs.

"The **Apollo** represents the culmination of nearly twenty years of technological advances in sputter deposition," stated John Bowers, vice president of customer operations at NEXX Systems. "This system really sets a new standard for faster, more economical processing of the critical metal layers requisite to tomorrow's electronic and solar devices."

The **Apollo** platform offers:

- the lowest capital price, up to \$1.0 million less than competitive systems, with the smallest footprint in the industry.
- the highest throughput and the ability to handle wafer sizes 100 mm to 300 mm, ranging in thickness from 100  $\mu\text{m}$  to 2 mm.
- electrostatic chuck (ESC) technology permits the processing of temperature-sensitive substrates, stress control for the processing of thick nickel films and for the backside metallization of thin wafers.
- enhanced deposition chamber pumping affords faster preventive maintenance, a key factor in improved uptime.

The **Apollo** software affords extremely flexible operation. Incorporating a field-proven, Ethernet-based, distributed control system, the **Apollo** is able to integrate wafer mapping and alignment at all wafer sizes.

MiniBatch software permits the user to process a recipe by batch or by cassette.

**About NEXX:** NEXX Systems brings exceptional technical expertise to the flip chip and advanced packaging markets. Our product lines provide the most efficient, yet affordable, systems of their kind: Apollo and Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).